

**Power Supply In Package Chip Market - Global Industry Size, Share, Trends, Opportunity, and Forecast, Segmented By Product (PSiP and PwrSoC), By Application (Telecom and IT, Automotive, Consumer Electronics, Medical Devices, and Military & Defense), By Region, By Competition, 2020-2030F**

Market Report | 2025-11-27 | 181 pages | TechSci Research

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**Report description:**

**Market Overview**

The Global Power Supply In Package Chip Market, valued at USD 3.06 Billion in 2024, is projected to experience a CAGR of 7.86% to reach USD 4.82 Billion by 2030. The Power Supply In Package (PSiP) chip integrates power management functions, such as DC-DC converters and voltage regulators, with other semiconductor components into a single compact package. This design optimizes power delivery, improves efficiency, and reduces the electronic system's footprint.

**Key Market Drivers**

The global Power Supply In Package chip market is significantly influenced by the continuous drive towards miniaturization and integration within electronic devices, alongside an escalating demand for energy-efficient power solutions. These twin imperatives directly impact the design and adoption of PSiP technologies, which are critical for optimizing power delivery and reducing system footprints across various applications. The broader semiconductor industry, which encompasses these power management solutions, demonstrated substantial growth, with Infineon Technologies AG reporting in November 2023 that its total revenue for fiscal year 2023 reached EUR16.309 billion, marking a 15 percent increase over the prior year.

**Key Market Challenges**

The complexity of thermal management presents a notable challenge directly hampering the growth of the Global Power Supply In Package Chip Market. The dense integration inherent in Power Supply In Package (PSiP) designs generates high power densities within a confined space. This necessitates robust heat dissipation mechanisms to prevent overheating, which is critical for ensuring stable operational performance and extending device longevity. Developing effective thermal solutions adds significant layers of complexity to the design and engineering processes for PSiP products.

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## Key Market Trends

The adoption of wide bandgap (WBG) semiconductor materials, such as silicon carbide and gallium nitride, represents a pivotal trend reshaping the Global Power Supply In Package Chip Market. These materials enable devices to operate at higher voltages, temperatures, and frequencies than traditional silicon, directly leading to greater power density and improved energy efficiency within compact PSiP designs. The superior electrical properties of WBG semiconductors facilitate faster switching speeds and reduced power losses, which are critical for the demanding performance requirements of modern electronics.

## Key Market Players

- Infineon Technologies AG
- Texas Instruments Incorporated
- Semiconductor Components Industries, LLC
- STMicroelectronics International N.V.
- Analog Devices, Inc.
- NXP Semiconductors N.V.
- Renesas Electronics Corporation
- Vishay Intertechnology, Inc.
- Panasonic Corporation
- Lextar Electronics Corporation

## Report Scope:

In this report, the Global Power Supply In Package Chip Market has been segmented into the following categories, in addition to the industry trends which have also been detailed below:

### -□Power Supply In Package Chip Market, By Product:

- o PSiP
- o PwrSoC

### -□Power Supply In Package Chip Market, By Application:

- o Telecom and IT
- o Automotive
- o Consumer Electronics
- o Medical Devices
- o Military & Defense

### -□Power Supply In Package Chip Market, By Region:

- o North America
  - United States
  - Canada
  - Mexico
- o Europe
  - France
  - United Kingdom
  - Italy
  - Germany
  - Spain
- o Asia Pacific
  - China
  - India
  - Japan
  - Australia
  - South Korea
- o South America

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- Brazil
- Argentina
- Colombia
- o Middle East & Africa
- South Africa
- Saudi Arabia
- UAE

#### Competitive Landscape

Company Profiles: Detailed analysis of the major companies presents in the Global Power Supply In Package Chip Market.

Available Customizations:

Global Power Supply In Package Chip Market report with the given market data, TechSci Research offers customizations according to a company's specific needs. The following customization options are available for the report:

Company Information

-□Detailed analysis and profiling of additional market players (up to five).

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